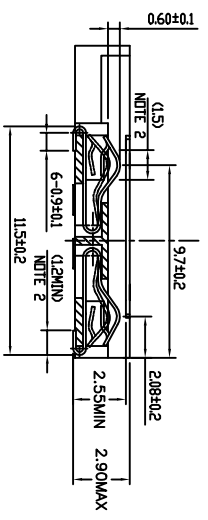
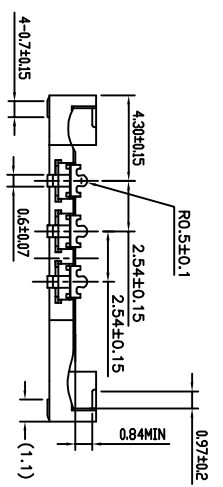
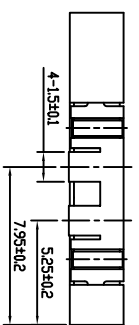
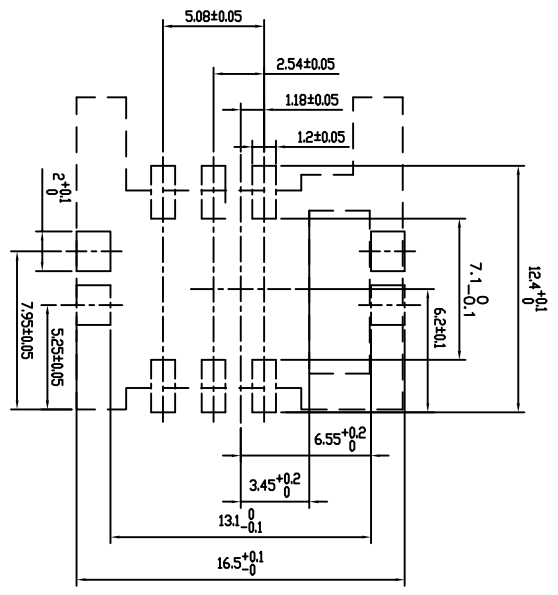
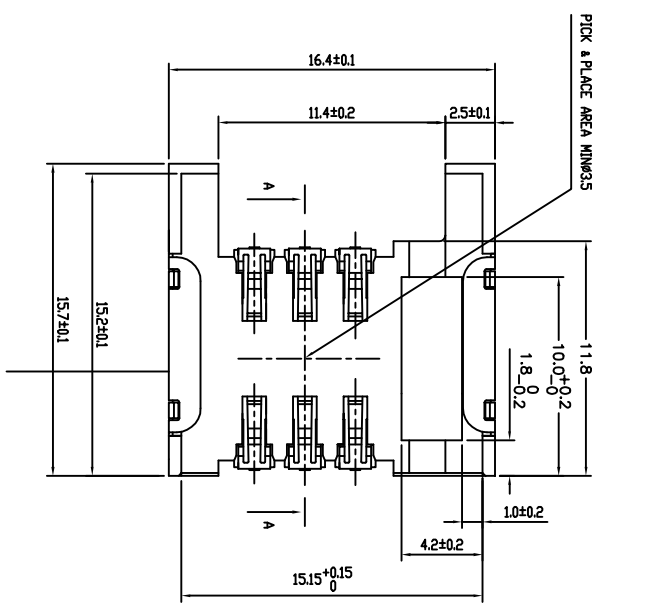


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NOTE:

1. Contacts chip cards according to ISD7816 and Plug In SIM-Cards.
2. Material: a) Housing: 30% GLASS-FILLED THERMOPLASTIC LCP BLACK UL 94V-0 b) Contact: Phosphor Bronze C519R-H Finish of contact: Contact point: Au over the gold plating thickness refers to part number system c) 2µm MIN Ni underplated Soldering point: 4µm SnPb over 2µm MIN Ni underplated d) Plate: stainless steel Finish of plate: 2µm MIN all Sn 2µm MIN Ni underplated e) Contact normal force for 0.5±0.2N 3. Packing tape & Reel. See packing method. 4. Material should be fulfilled Amphenol SPEC# SMM001

Order Number: CAD-06W1-29X  
 0-Unplated  
 1-0.76 µm MIN Gold  
 2-0.38 µm MIN Gold  
 3-Gold Flash 0.025 µm MIN

REVISIONS				
REV	DESCR	DATE	APPROVED	
B	HK2561	RELEASE TO PRODUCTION	5/22/03	Michael P
C	HK2604	TO REDESIGN OF THE METAL CUP	7/28/03	Michael P
D	HK2727	CHANGE THE SPEC:0.65V/-0.1 TO 0.60V/-0.1	10/21/03	Michael P

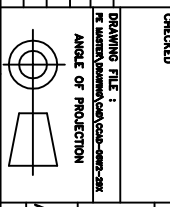
UNLESS OTHERWISE SPECIFIED  
 TOLERANCES  
 U.S. METRIC  
 X +/- 0.20  
 XX +/- 0.10  
 ANGLES +/- 2°  
 REMOVE SHARP EDGES

APPROVAL	DATE
DRAWN: Sedehdim	10/21/03
CHECKED: Michael P	10/21/03
CHECKED:	

6 Pin Wingblock  
 Smartcard Connector  
 Amphenol

CUSTOMER DRAWING

DIMENSIONS	
U.S.	METRIC
0.005	0.10
0.002	0.05



SIZE	SCALE	SHEET	REV.
A3	CAD-06W1-29X	1 OF 1	D